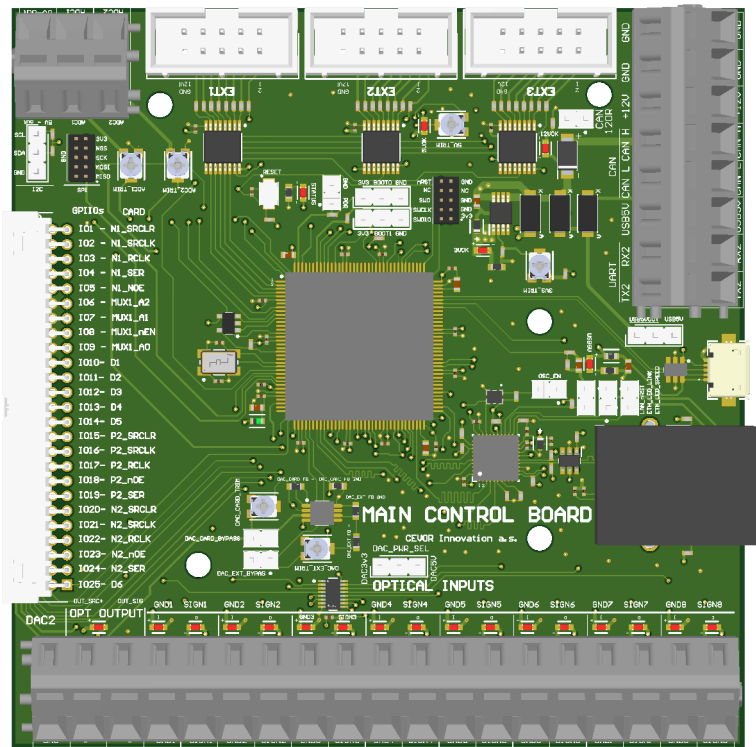
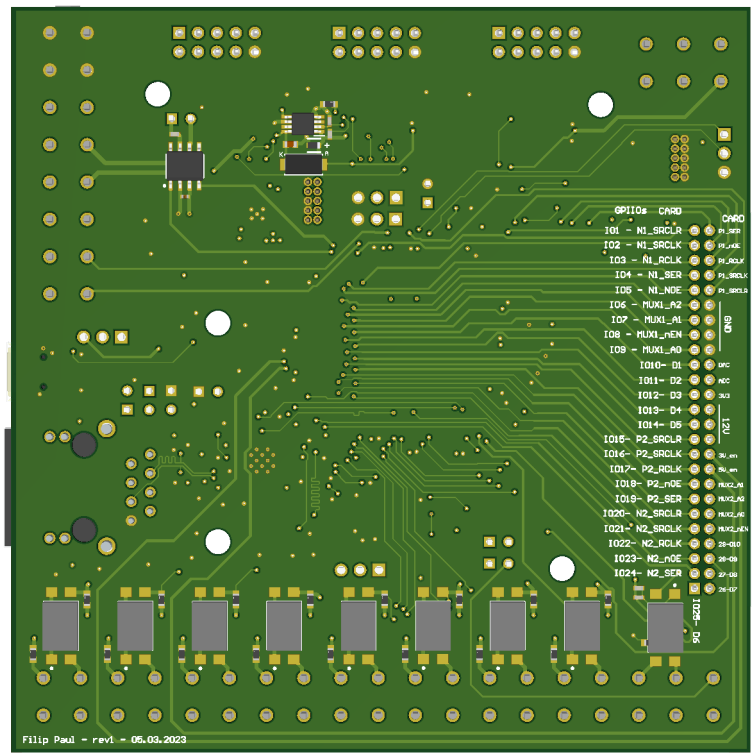


MAIN CONTROL BOARD

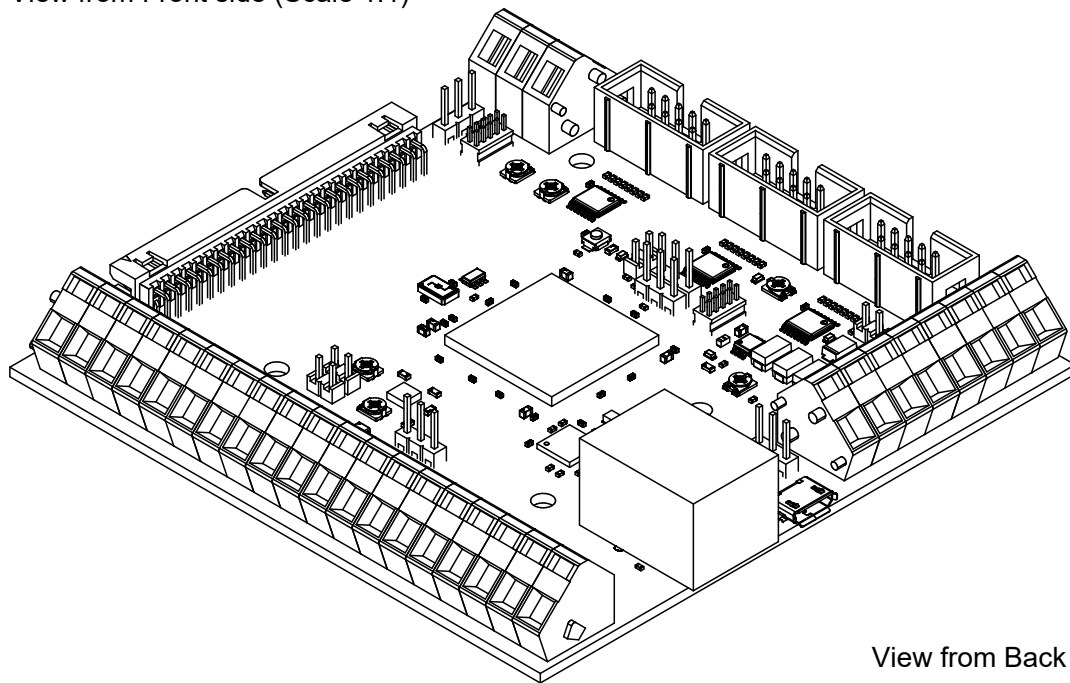
Realistic View



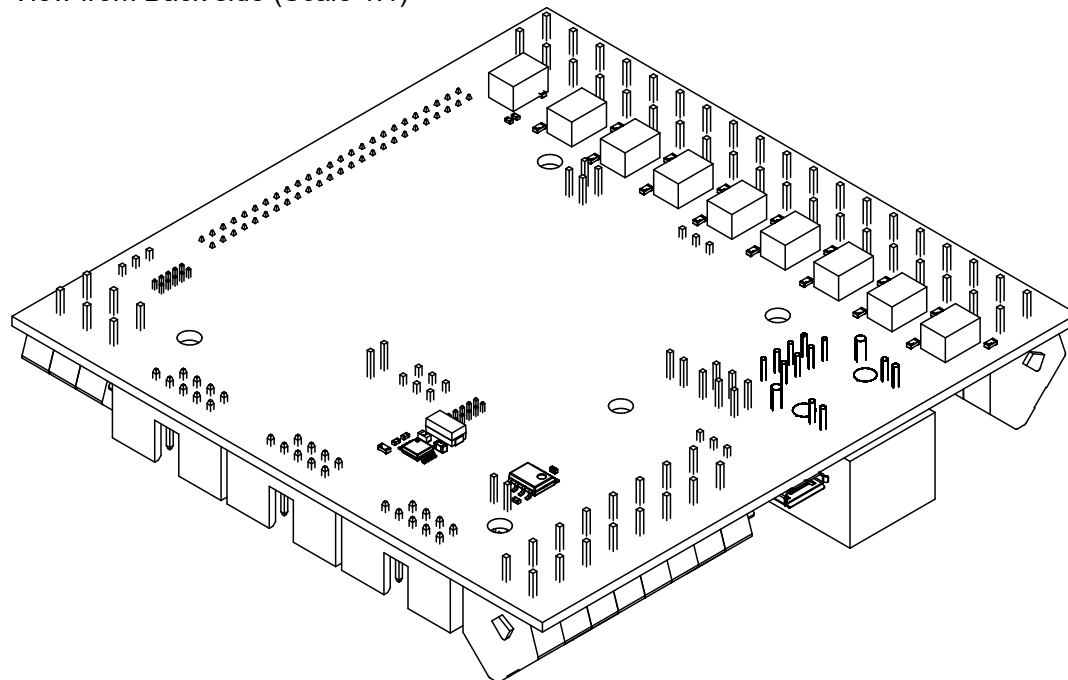
Realistic View



View from Front side (Scale 1:1)

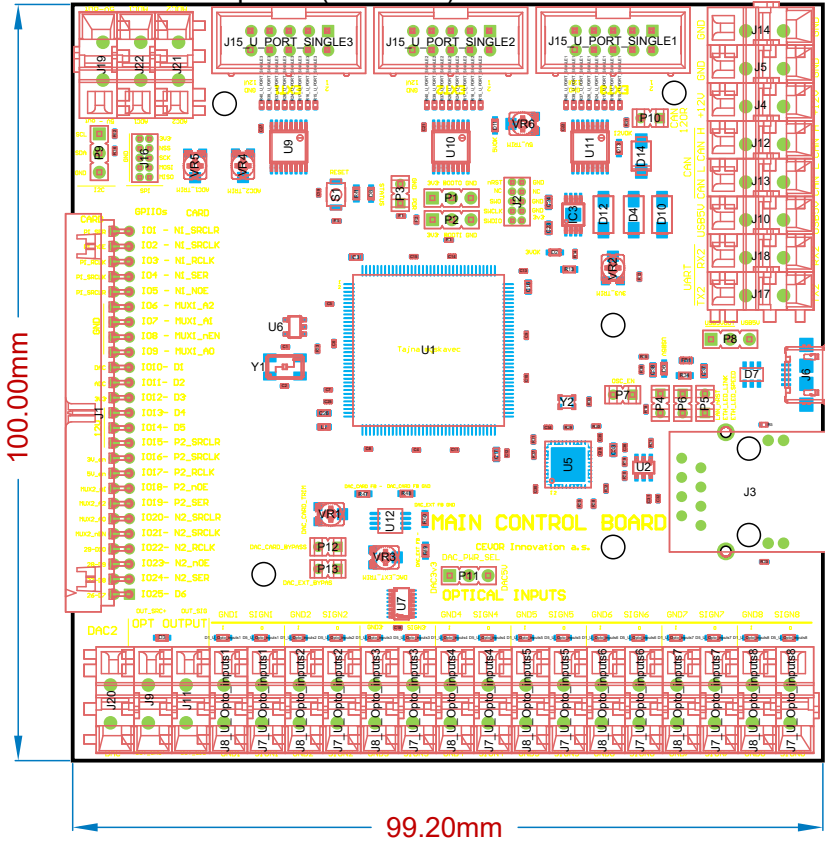


View from Back side (Scale 1:1)

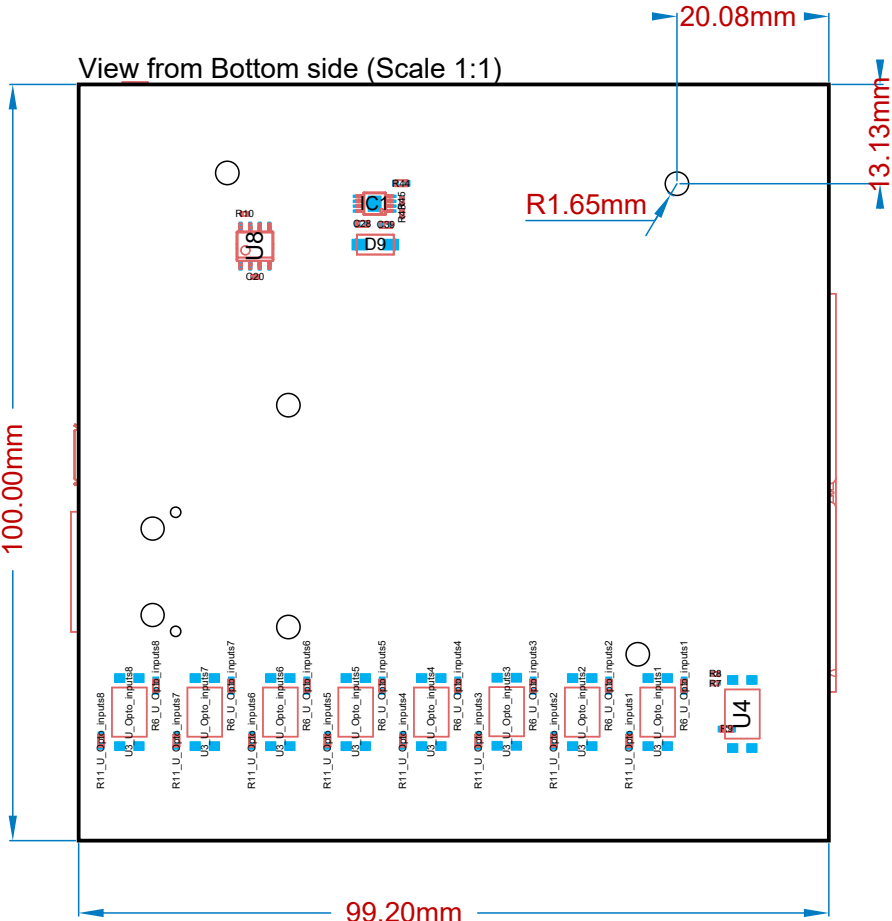


ASSEMBLY DRAWING

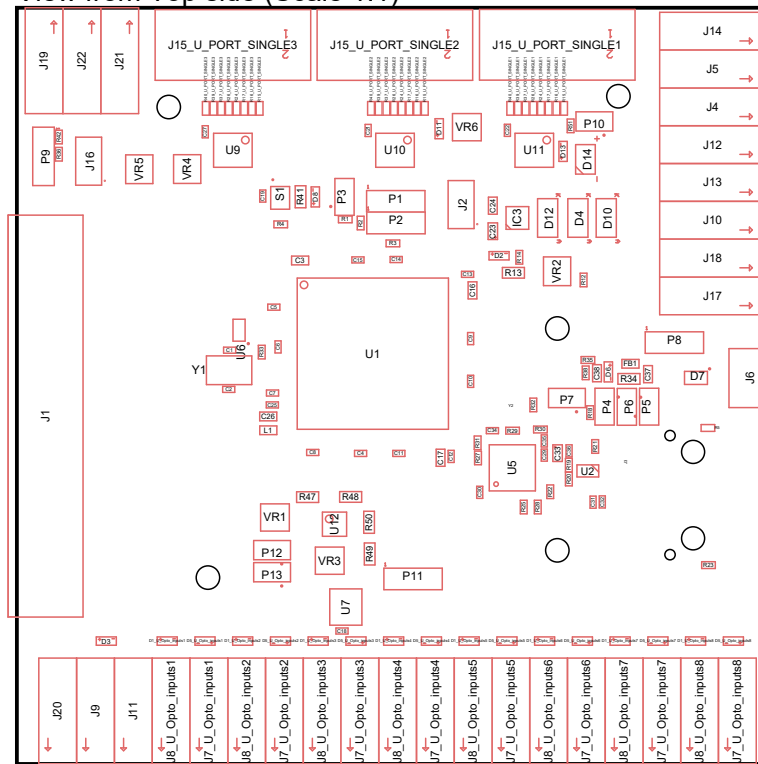
View from Top side (Scale 1:1)



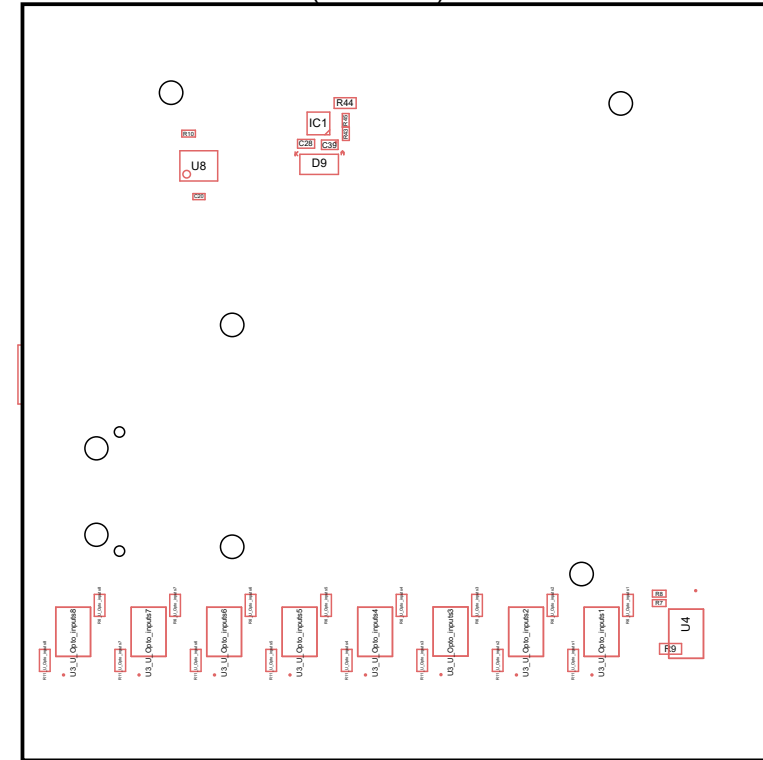
View from Bottom side (Scale 1:1)



View from Top side (Scale 1:1)



View from Bottom side (Scale 1:1)



FABRICATION DRAWING

Layer Stack Legend

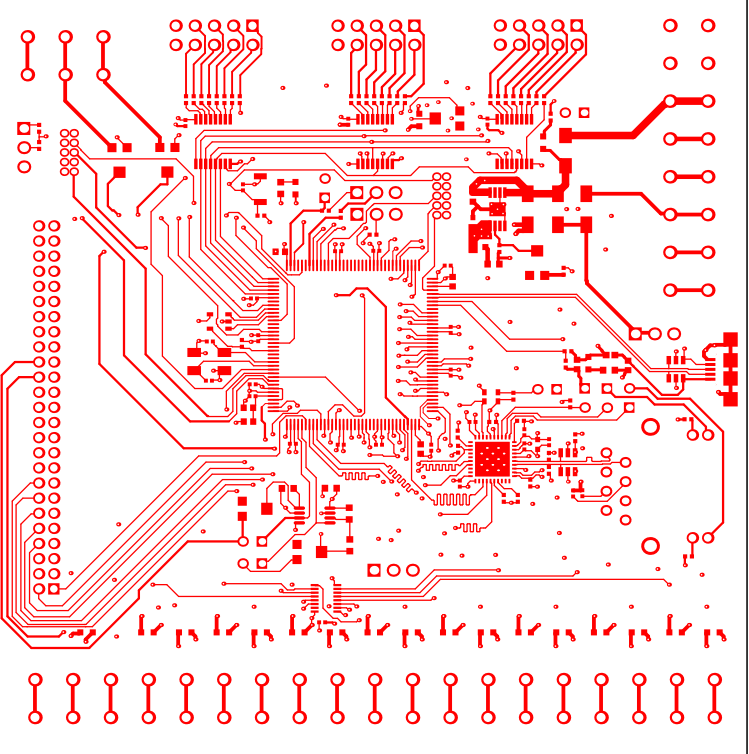
Material	Layer	Thickness	Dielectric Material	Type	Gerber
	Top Overlay			Legend	GTO
Surface Material	Top Solder	0.02mm	Solder Resist	Solder Mask	GTS
JLC_6_TOP	Top Layer	0.04mm		Signal	GTL
Prepreg		0.10mm	JLC3313	Dielectric	
JLC_6_INNER	Inner Layer 2(GND)	0.02mm		Signal	G1
Prepreg		0.55mm	JLCcore	Dielectric	
Copper	Inner Layer 3	0.02mm		Signal	G2
		0.11mm	LC2116	Dielectric	
Copper	Inner Layer 4	0.02mm		Signal	G3
Prepreg		0.55mm	JLCcore	Dielectric	
JLC_6_INNER	Inner Layer 5	0.02mm		Signal	G4
Prepreg		0.10mm	JLC3313	Dielectric	
JLC_6_TOP	Bottom Layer 1	0.04mm		Signal	GBL
Surface Material	Bottom Solder	0.02mm	Solder Resist	Solder Mask	GBS
	Bottom Overlay			Legend	GBO

Total thickness: 1.59mm

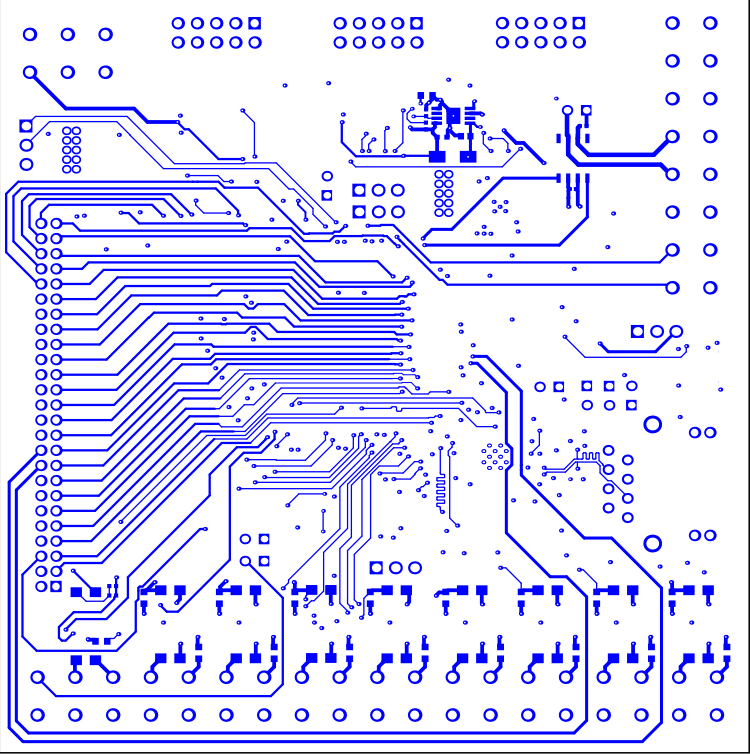
Impedance control stackup:
USB (top layer):
USB_D_P and USB_D_N -> 90 Ohms diff, 50 GND

ETHERNET (top layer):
TD_P and TD_N -> 100Ohms diff, 50 GND
TD_P and RD_N -> 100Ohms diff, 50GND

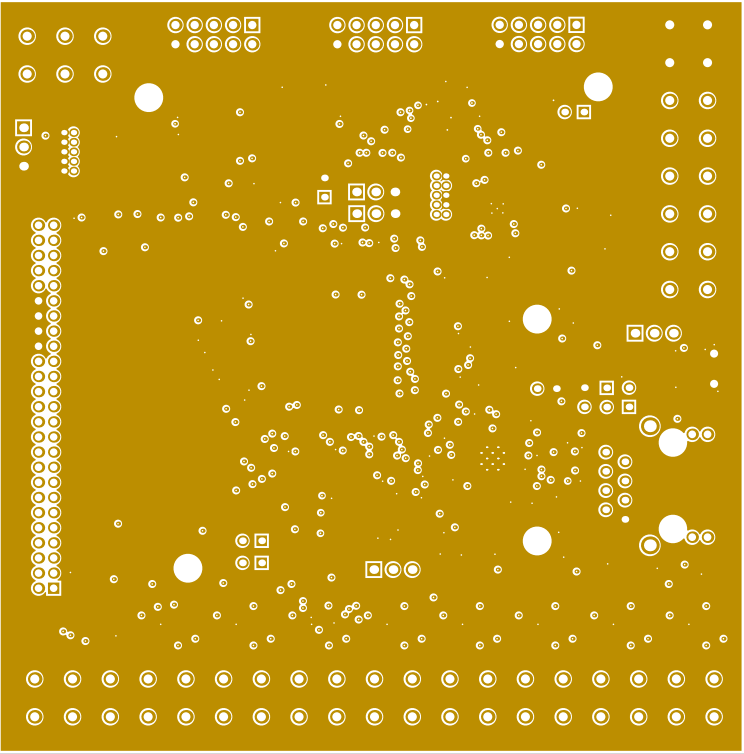
Top Layer (Scale 1:1)



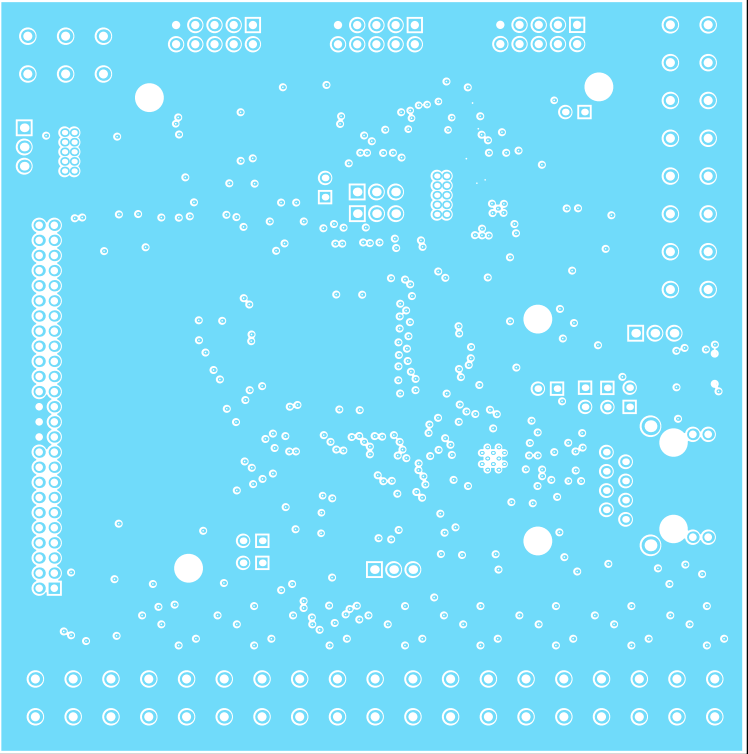
Bottom Layer 1 (Scale 1:1)



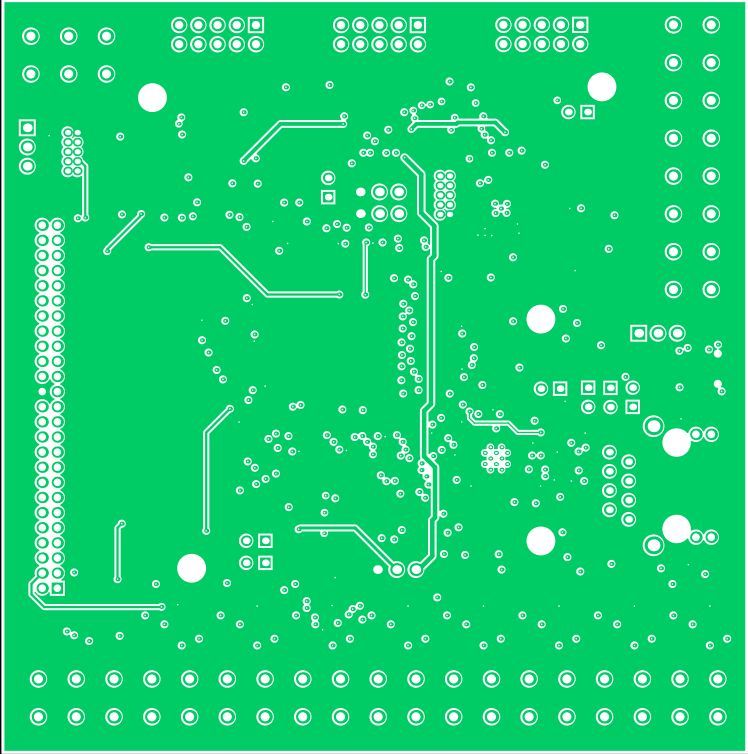
Inner Layer 2(GND) (Scale 1:1)



Inner Layer 3 (Scale 1:1)



Inner Layer 4 (Scale 1:1)



Inner Layer 5 (Scale 1:1)

